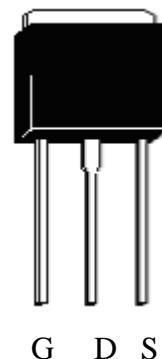


N -Channel Logic Level Enhancement Mode Power MOSFET

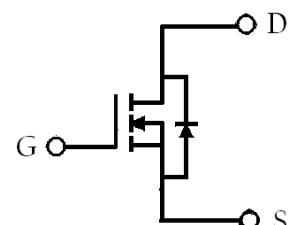
Features:

- Low Gate Charge
- Simple Drive Requirement
- Pb-free lead plating package

TO-251



G D S



G : Gate D : Drain

S : Source

Ordering Information

Device	Package	Shipping
KIN6515	TO-251 (RoHS compliant and halogen-free package)	80 pcs/tube, 50 tubes/box

Absolute Maximum Ratings (T_c=25°C, unless otherwise noted)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V _{DS}	150	V
Gate-Source Voltage	V _{GS}	±16	
Continuous Drain Current @ V _{GS} =10V, T _c =25°C	I _D	20	A
Continuous Drain Current @ V _{GS} =10V, T _c =100°C		14	
Pulsed Drain Current *1	I _{DM}	60	A
Avalanche Current	I _{AS}	20	
Avalanche Energy @ L=0.47mH, I _D =20A, R _G =25Ω *3	E _{AS}	94	mJ
Repetitive Avalanche Energy @ L=0.05mH *2	E _{AR}	2.5	
Total Power Dissipation @ T _c =25°C	P _D	60	W
Total Power Dissipation @ T _c =100°C		30	
Operating Junction and Storage Temperature Range	T _j , T _{stg}	-55~+175	°C

Note : *1. Pulse width limited by maximum junction temperature.

*2. Duty cycle ≤ 1%.

*3. 100% tested by conditions of L=0.47mH, I_{AS}=12A, V_{GS}=10V, V_{DD}=50V

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	R _{θJC}	2.5	°C/W
Thermal Resistance, Junction-to-ambient, max	R _{θJA}	100	

Characteristics (T_c=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	150	-	-	V	V _{GS} =0V, I _D =250μA
V _{GS(th)}	0.45	-	1.20		V _{DS} =V _{GS} , I _D =250μA
I _{GSS}	-	-	±100	nA	V _{GS} =±12V, V _{DS} =0V
I _{DSS}	-	-	1		V _{DS} =120V, V _{GS} =0V
	-	-	25	μA	V _{DS} =100V, V _{GS} =0V, T _j =125°C
R _{DS(ON)} *1	-	60	75	mΩ	V _{GS} =10V, I _D =15A
	-	59	75		V _{GS} =5V, I _D =10A
	-	60	75		V _{GS} =3V, I _D =3A
G _{FS} *1	-	48	-	S	V _{DS} =5V, I _D =10A
Dynamic					
Q _g *1, 2	-	30	-	nC	I _D =10A, V _{DS} =80V, V _{GS} =5V
Q _{gs} *1, 2	-	4.8	-		
Q _{gd} *1, 2	-	16	-		
t _{d(ON)} *1, 2	-	23	-	ns	V _{DS} =75V, I _D =1A, V _{GS} =4.5V, R _G =6Ω
t _r *1, 2	-	22	-		
t _{d(OFF)} *1, 2	-	91	-		
t _f *1, 2	-	63	-		

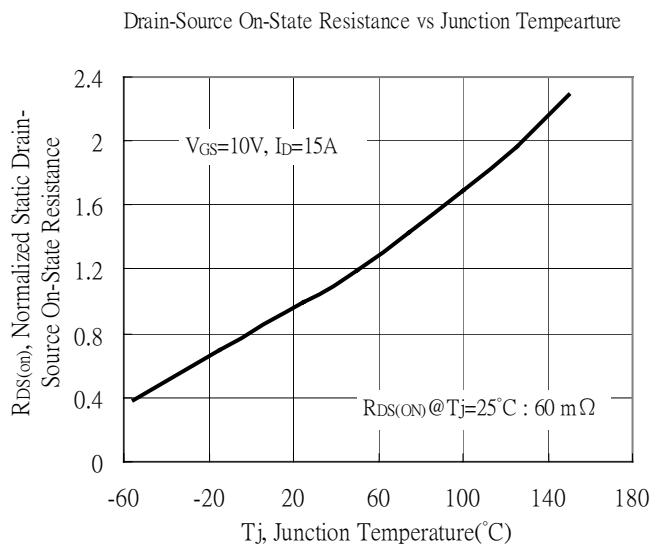
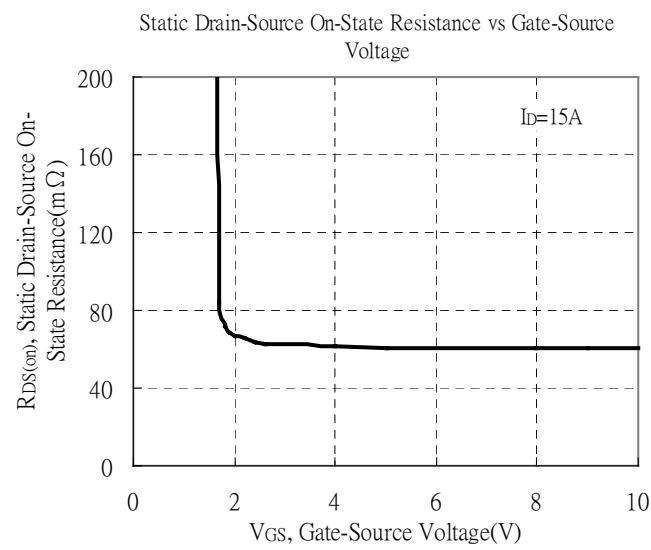
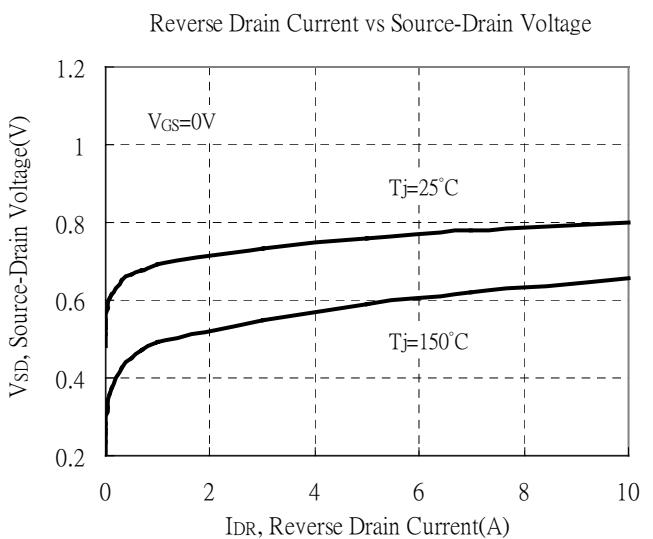
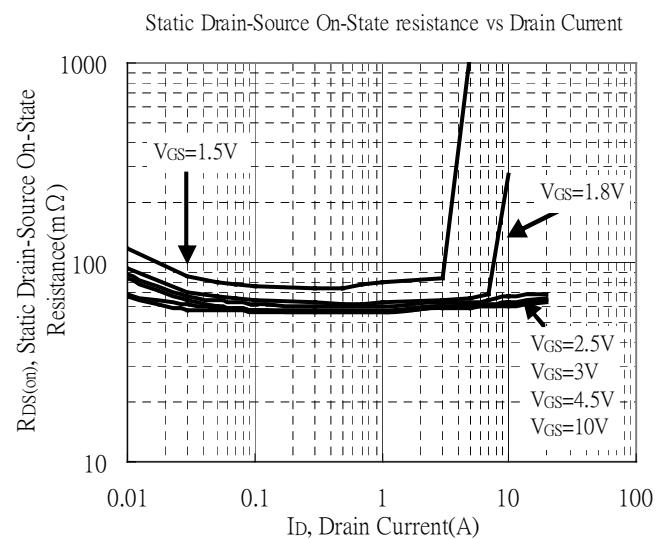
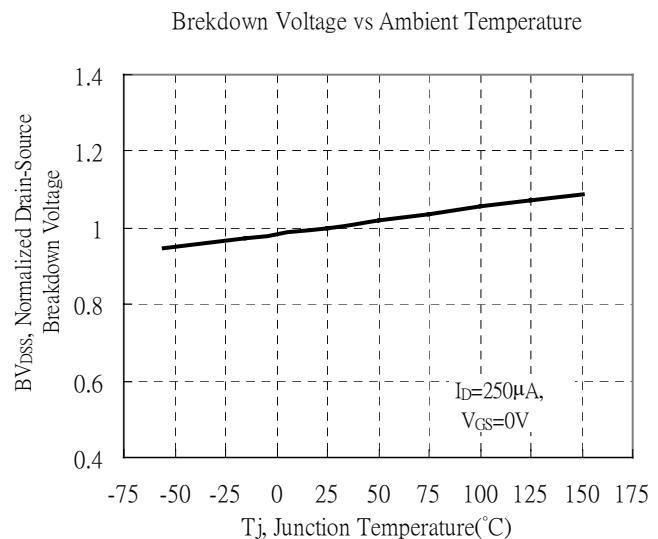
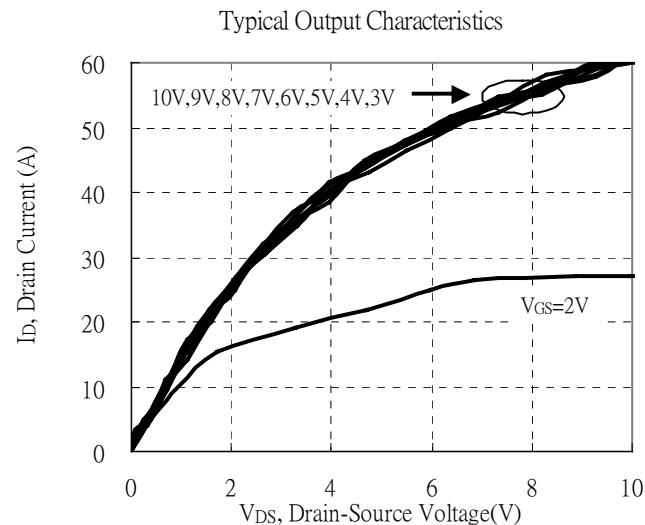
Ciss	-	2282	-	pF	V _{GS} =0V, V _{DS} =25V, f=1MHz
Coss	-	120	-		
Crss	-	66	-		
Source-Drain Diode					
I _S *1	-	-	20	A	
I _{SM} *3	-	-	60		
V _{SD} *1	-	0.85	1.3	V	I _F =I _S , V _{GS} =0V
t _{rr}	-	50	-	ns	
Q _{rr}	-	120	-	nC	I _F =20A, dI _F /dt=100A/μs

Note : *1.Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

*2.Independent of operating temperature

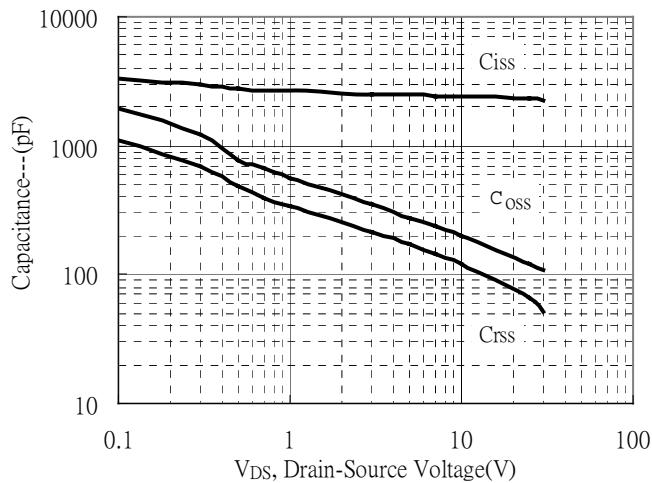
*3.Pulse width limited by maximum junction temperature.

Typical Characteristics

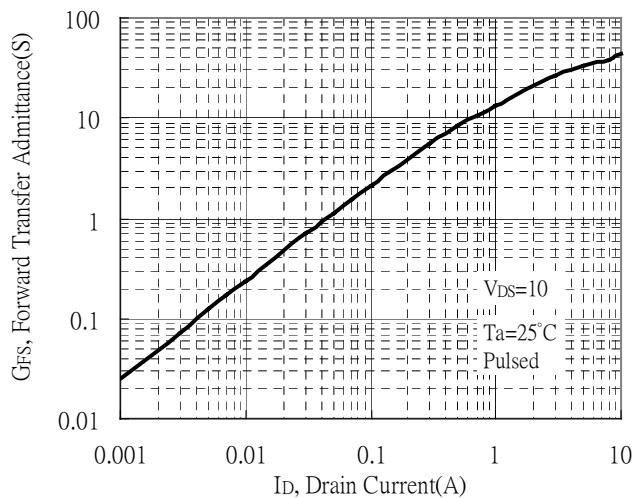


Typical Characteristics (Cont.)

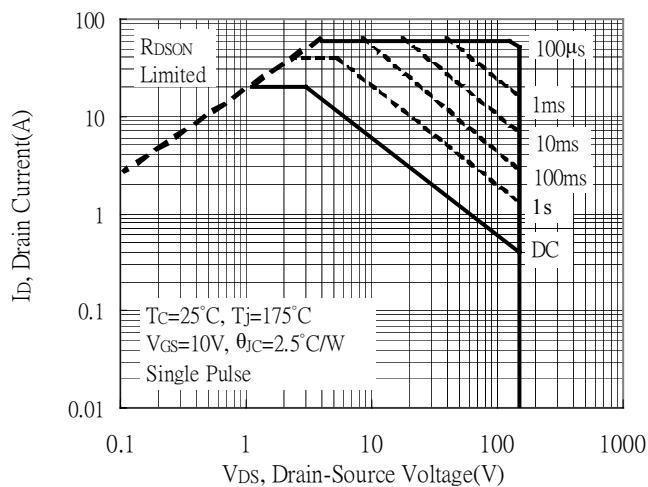
Capacitance vs Drain-to-Source Voltage



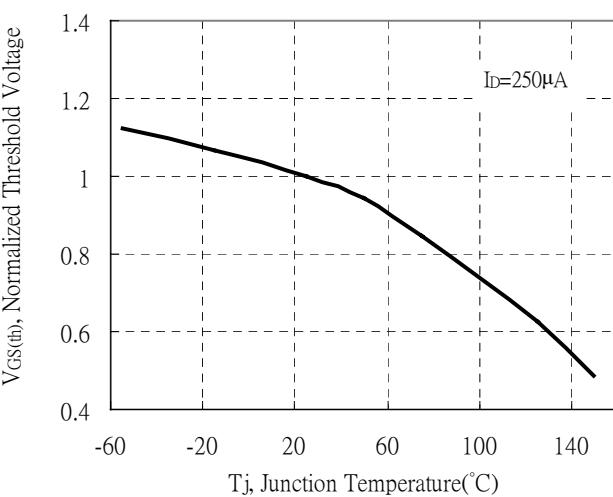
Forward Transfer Admittance vs Drain Current



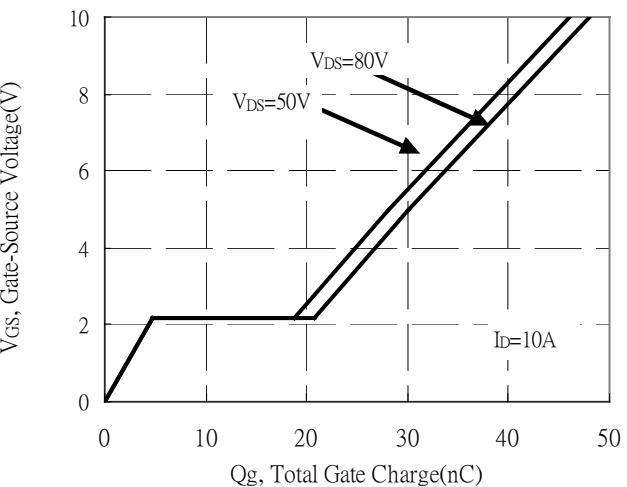
Maximum Safe Operating Area



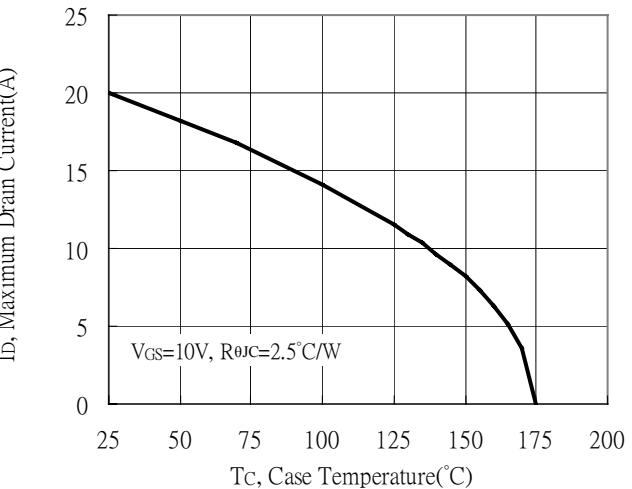
Threshold Voltage vs Junction Temperature



Gate Charge Characteristics

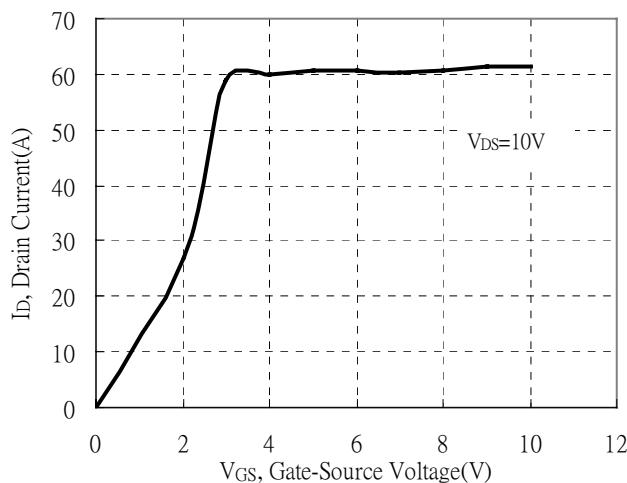


Maximum Drain Current vs Case Temperature

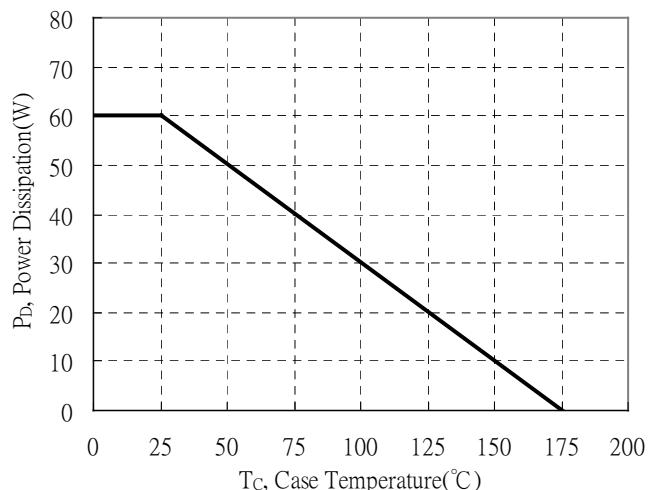


Typical Characteristics (Cont.)

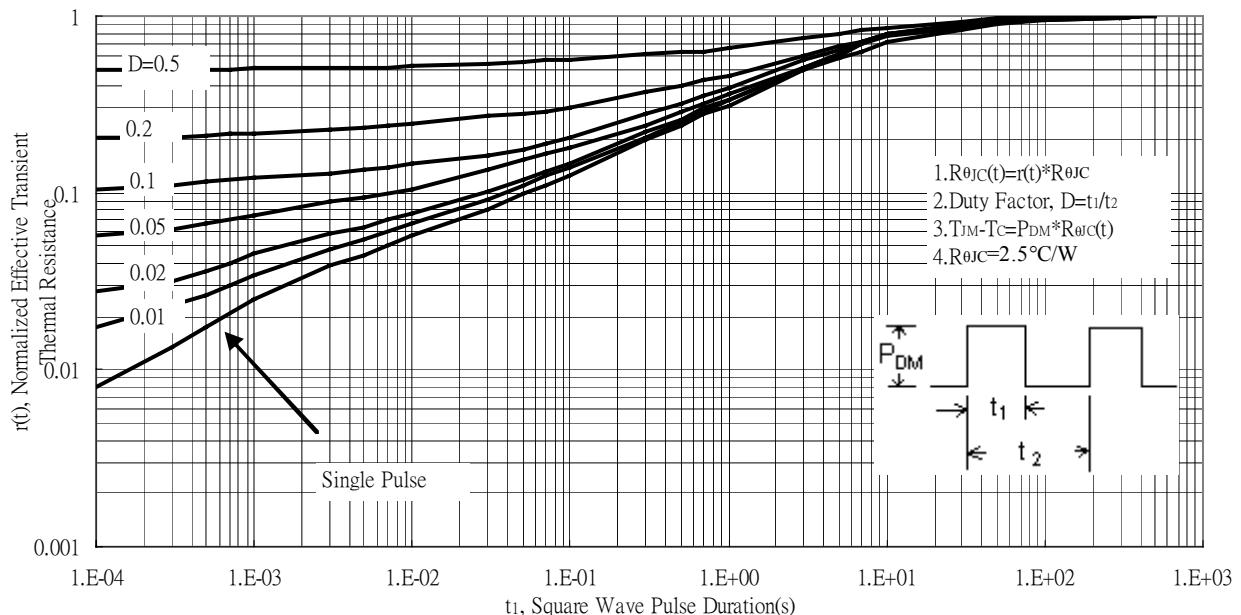
Typical Transfer Characteristics



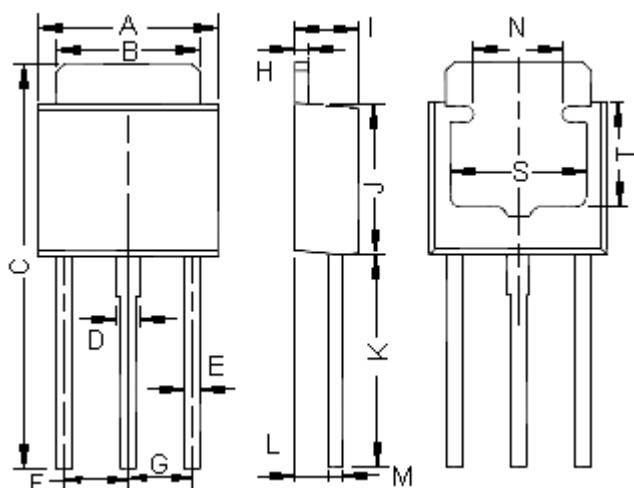
Power Derating Curve



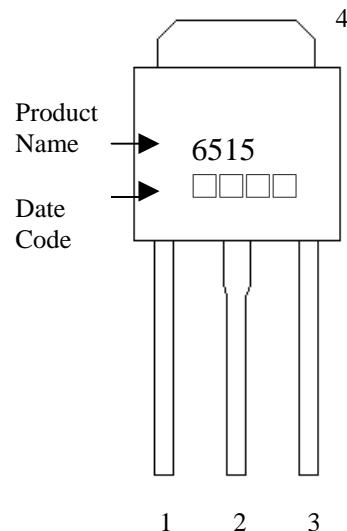
Transient Thermal Response Curves



TO-251 Dimension



Marking:



Style: Pin 1.Gate 2.Drain 3.Source
4 Drain

3-Lead TO-251 Plastic Package

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2500	0.2618	6.35	6.65	I	0.0866	0.0945	2.20	2.40
B	0.2047	0.2126	5.20	5.40	J	0.2126	0.2244	5.40	5.70
C	0.5709	0.5866	14.50	14.90	K	0.2992	0.3071	7.60	7.80
D	0.0276	0.0354	0.70	0.90	L	0.0453	0.0492	1.15	1.25
E	0.0199	0.0276	0.50	0.70	M	0.0169	0.0228	0.43	0.58
F	0.0886	0.0925	2.25	2.35	N	0.1181	REF	3.00	REF
G	0.0886	0.0925	2.25	2.35	S	0.1969	REF	5.00	REF
H	0.0169	0.0228	0.43	0.58	T	0.1496	REF	3.80	REF